

FAN73711

High-Current, High-Side Gate Drive IC

Features

- Floating Channel for Bootstrap Operation to +600V
- 4A/4A Sourcing/Sinking Current Driving Capability
- Common-Mode dv/dt Noise Canceling Circuit
- 3.3V and 5V Input Logic Compatible
- Output In-phase with Input Signal
- Under-Voltage Lockout for V_{BS}
- Built-In Shunt Regulator on V_{DD} and V_{BS}
- 8-Lead Small Outline Package (SOP)

Applications

- High-Speed Gate Driver
- Sustain Switch Driver in PDP Application
- Energy Recovery Circuit Switch Driver in PDP Application
- High-Power Buck Converter
- Motor Drive Inverter

Description

The FAN73711 is a monolithic high-side gate drive IC that can drive high-speed MOSFETs and IGBTs operating up to +600V. It has a buffered output stage with all NMOS transistors designed for high pulse current driving capability and minimum cross-conduction.

Fairchild's high-voltage process and common-mode noise canceling techniques provide stable operation of the high-side driver under high dv/dt noise circumstances. An advanced level-shift circuit offers high-side gate driver operation up to $V_S = -9.8V$ (typical) for $V_{BS} = 15V$. The UVLO circuit prevents malfunction when V_{BS} is lower than the specified threshold voltage.

The high-current and low-output voltage drop feature makes this device suitable for sustain and energy-recovery circuit switches driver in the plasma display panel application, motor drive inverter, switching power supply, and high-power DC-DC converter applications.

8-SOP



Ordering Information

Part Number	Operating Temperature Range	Package	 Eco Status	Packing Method
FAN73711M	40°C ~ 125°C	8-SOP	RoHS	Tube
FAN73711MX				Tape and Reel



For Fairchild's definition of Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

Typical Application Diagrams

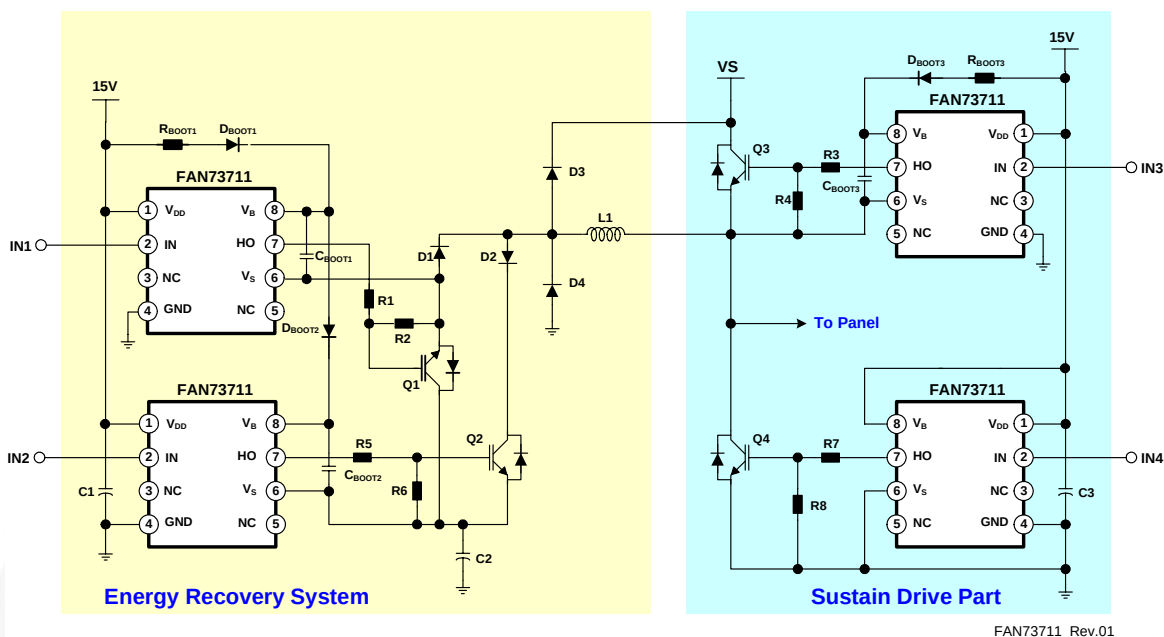


Figure 1. Floated Bi-Directional Switch and Half-Bridge Driver: PDP Application

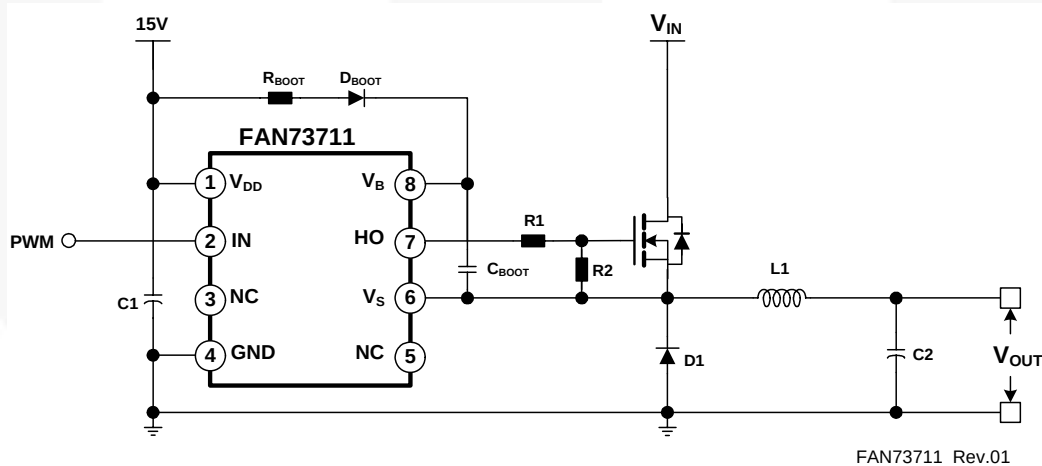


Figure 2. Step-Down (Buck) DC-DC Converter Application

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. $T_A=25^{\circ}\text{C}$ unless otherwise specified.

Symbol	Characteristics	Min.	Max.	Unit
V_S	High-Side Floating Offset Voltage ⁽¹⁾	$V_B - V_{SHUNT}$	$V_B + 0.3$	V
V_B	High-Side Floating Supply Voltage	-0.3	625.0	V
V_{HO}	High-Side Floating Output Voltage	$V_S - 0.3$	$V_B + 0.3$	V
V_{DD}	Low-Side and Logic Supply Voltage ⁽¹⁾	-0.3	V_{SHUNT}	V
V_{IN}	Logic Input Voltage	-0.3	$V_{DD} + 0.3$	V
dV_S/dt	Allowable Offset Voltage Slew Rate		± 50	V/ns
P_D	Power Dissipation ^(2, 3, 4)		0.625	W
θ_{JA}	Thermal Resistance		200	$^{\circ}\text{C/W}$
T_J	Junction Temperature	-55	+150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature	-55	+150	$^{\circ}\text{C}$

Notes:

1. This IC contains a shunt regulator on V_{DD} and V_{BS} . This supply pin should not be driven by a low-impedance voltage source greater than the V_{SHUNT} specified in the electrical characteristics section.
2. Mounted on 76.2 x 114.3 x 1.6mm PCB (FR-4 glass epoxy material).
3. Refer to the following standards:
JESD51-2: Integral circuits thermal test method environmental conditions, natural convection, and
JESD51-3: Low effective thermal conductivity test board for leaded surface-mount packages.
4. Do not exceed power dissipation (P_D) under any circumstances.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V_B	High-Side Floating Supply Voltage	$V_S + 10$	$V_S + 20$	V
V_S	High-Side Floating Supply Offset Voltage	$6 - V_{DD}$	600	V
V_{HO}	High-Side Output Voltage	V_S	V_B	V
V_{IN}	Logic Input Voltage	GND	V_{DD}	V
V_{DD}	Supply Voltage	10	20	V
T_A	Operating Ambient Temperature	-40	+125	$^{\circ}\text{C}$

Electrical Characteristics

$V_{BIAS}(V_{DD}, V_{BS})=15.0V$, $T_A = 25^\circ C$, unless otherwise specified. The V_{IN} and I_{IN} parameters are referenced to GND. The V_O and I_O parameters are relative to V_S and are applicable to the respective output HO.

Symbol	Characteristics	Test Condition	Min.	Typ.	Max.	Unit
Power Supply Section						
I_{QDD}	Quiescent V_{DD} Supply Current	$V_{IN}=0V$ or $5V$		25	70	μA
I_{PDD}	Operating V_{DD} Supply Current	$f_{IN}=20KHz$, No Load		35	100	μA
Bootstrapped Supply Section						
V_{BSUV+}	V_{BS} Supply Under-Voltage Positive-Going Threshold Voltage	$V_{BS}=\text{Sweep}$	8.0	9.0	10.0	V
V_{BSUV-}	V_{BS} Supply Under-Voltage Negative-Going Threshold Voltage	$V_{BS}=\text{Sweep}$	7.3	8.3	9.3	V
V_{BSHYS}	V_{BS} Supply Under-Voltage Lockout Hysteresis Voltage	$V_{BS}=\text{Sweep}$		0.7		V
I_{LK}	Offset Supply Leakage Current	$V_B=V_S=625V$			10	μA
I_{QBS}	Quiescent V_{BS} Supply Current	$V_{IN}=0V$ or $5V$		60	120	μA
I_{PBS}	Operating V_{BS} Supply Current	$C_{LOAD}=1000pF$, $f_{IN}=20KHz$, rms Value		470	800	μA
Shung Regulator Section						
V_{SHUNT}	V_{DD} and V_{BS} Shunt Regulator Clamping Voltage	$V_{DD}=\text{Sweep}$ or $V_{BS}=\text{Sweep}$ $I_{SHUNT}=5mA$	21	23	25	V
Input Logic Section						
V_{IH}	Logic "1" Input Voltage		2.5			V
V_{IL}	Logic "0" Input Voltage				0.8	V
I_{IN+}	Logic Input High Bias Current	$V_{IN}=5V$		40	65	μA
I_{IN-}	Logic Input Low Bias Current	$V_{IN}=0V$			2	μA
R_{IN}	Input Pull-Down Resistance		90	110		$K\Omega$
Gate Driver Output Section						
V_{OH}	High Level Output Voltage ($V_{BIAS} - V_O$)	No Load			1.2	V
V_{OL}	Low Level Output Voltage	No Load			30	mV
I_{O+}	Output High, Short-Circuit Pulsed Current ⁽⁵⁾	$V_{HO}=0V$, $V_{IN}=5V$, $PW \leq 10\mu s$	3	4		A
I_{O-}	Output Low, Short-Circuit Pulsed Current ⁽⁵⁾	$V_{HO}=15V$, $V_{IN}=0V$, $PW \leq 10\mu s$	3	4		A
V_S	Allowable Negative V_S Pin Voltage for IN Signal Propagation to HO			-9.8	-7.0	V

Note:

5. These parameters guaranteed by design.

Dynamic Electrical Characteristics

$V_{DD}=V_{BS}=15V$, $GND=0V$, $C_{LOAD}=1000pF$, $T_A=25^\circ C$, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
t_{on}	Turn-On Propagation Delay Time	$V_S=0V$		150	210	ns
t_{off}	Turn-Off Propagation Delay Time	$V_S=0V$		150	210	ns
t_r	Turn-On Rise Time			25	50	ns
t_f	Turn-Off Fall Time			15	40	ns

Typical Characteristics

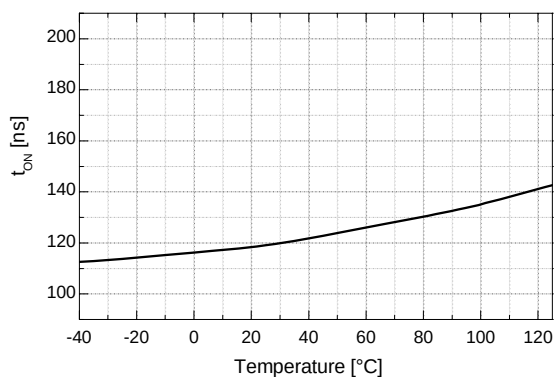


Figure 5. Turn-On Propagation Delay vs. Temperature

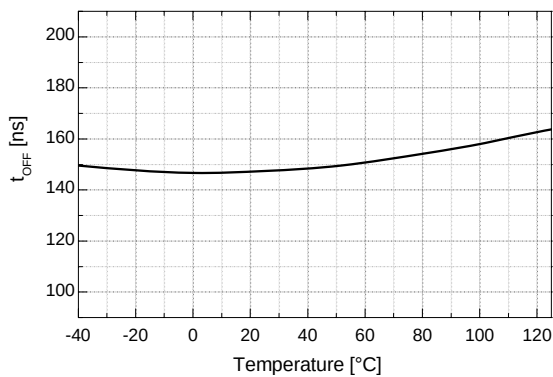


Figure 6. Turn-Off Propagation Delay vs. Temperature

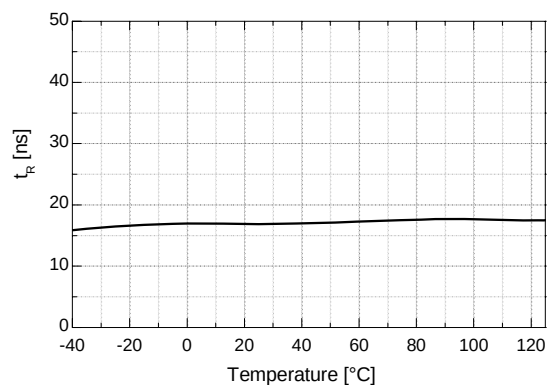


Figure 7. Turn-On Rise Time vs. Temperature

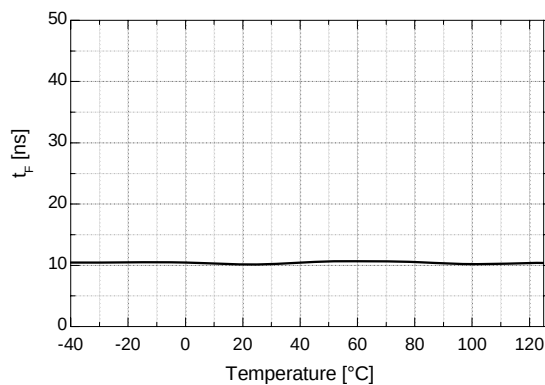


Figure 8. Turn-Off Fall Time vs. Temperature

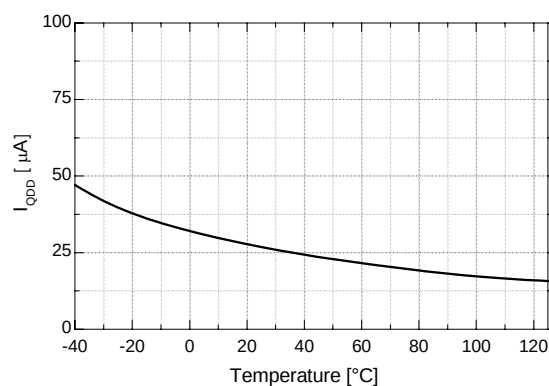


Figure 9. Quiescent V_{DD} Supply Current vs. Temperature

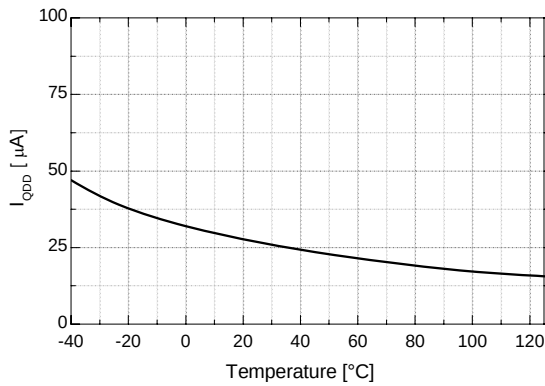


Figure 10. Quiescent V_{BS} Supply Current vs. Temperature

Typical Characteristics (Continued)

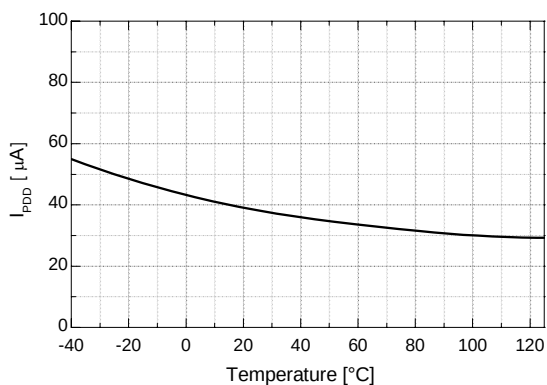
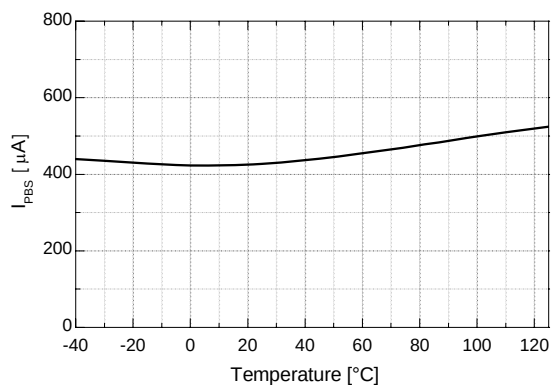
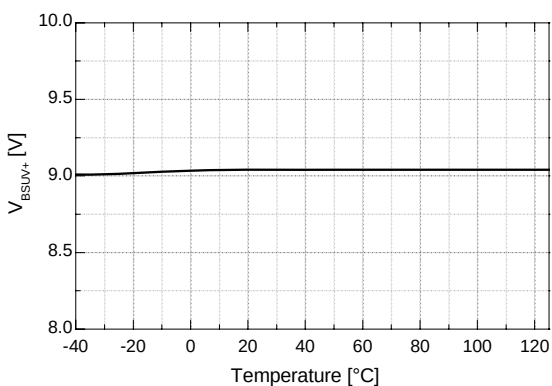
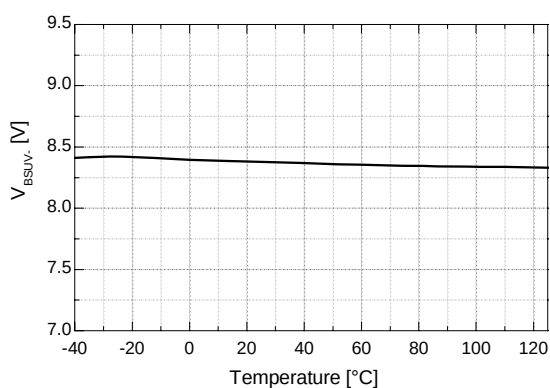
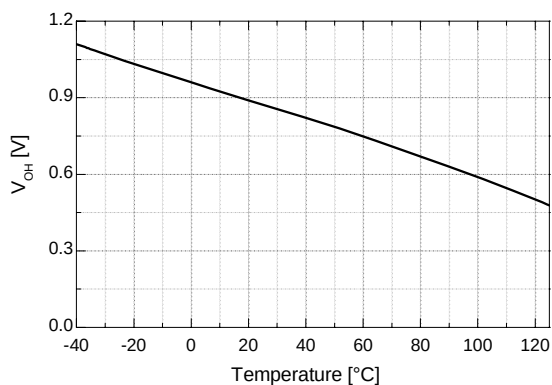
Figure 11. Operating V_{DD} Supply Current vs. TemperatureFigure 12. Operating V_{BS} Supply Current vs. TemperatureFigure 13. V_{BS} UVLO+ vs. TemperatureFigure 14. V_{BS} UVLO- vs. Temperature

Figure 15. High-Level Output Voltage vs. Temperature

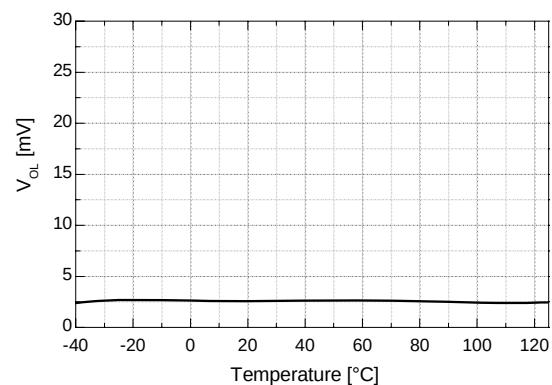


Figure 16. Low-Level Output Voltage vs. Temperature

Typical Characteristics (Continued)

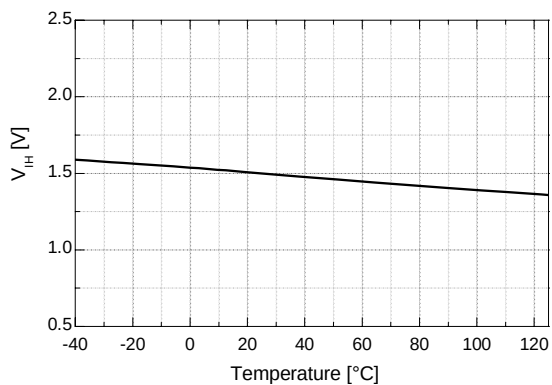


Figure 17. Logic High Input Voltage vs. Temperature

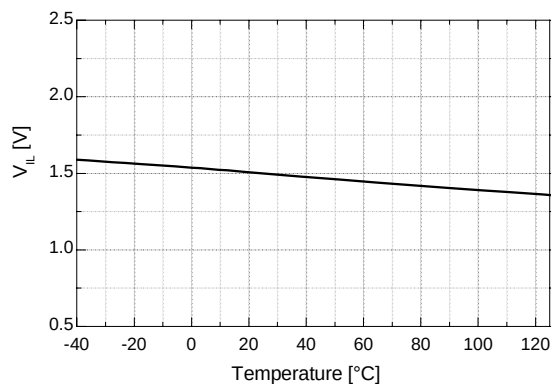


Figure 18. Logic Low Input Voltage vs. Temperature

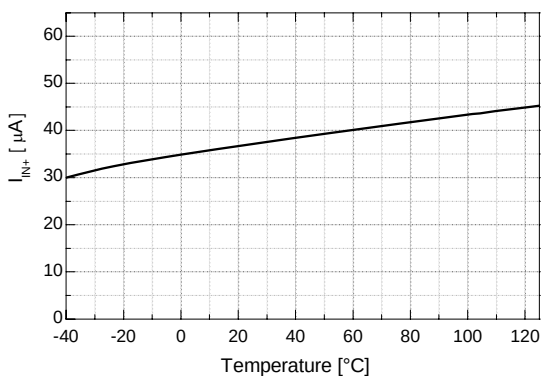


Figure 19. Logic Input High Bias Current vs. Temperature

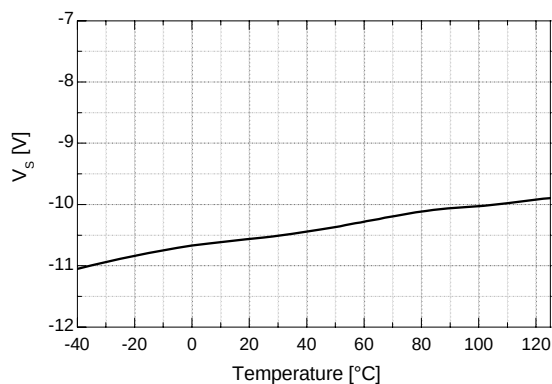


Figure 20. Allowable Negative V_S Voltage vs. Temperature

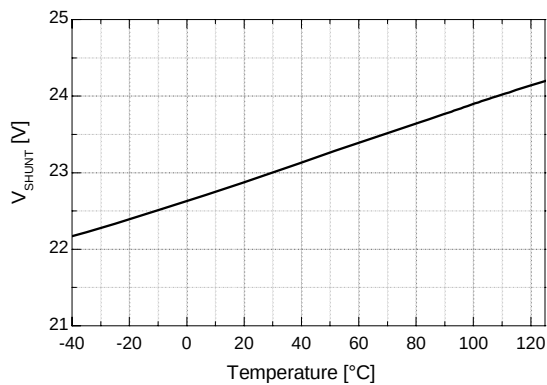


Figure 21. Shunt Regulator Clamping Voltage vs. Temperature

Switching Time Definitions

Timing Diagram

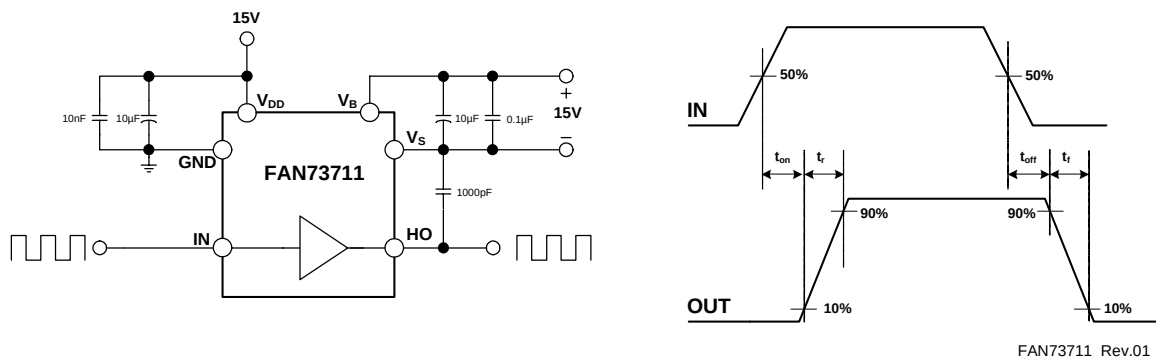


Figure 22. Switching Time Test Circuit and Waveform Definitions

Package Dimensions

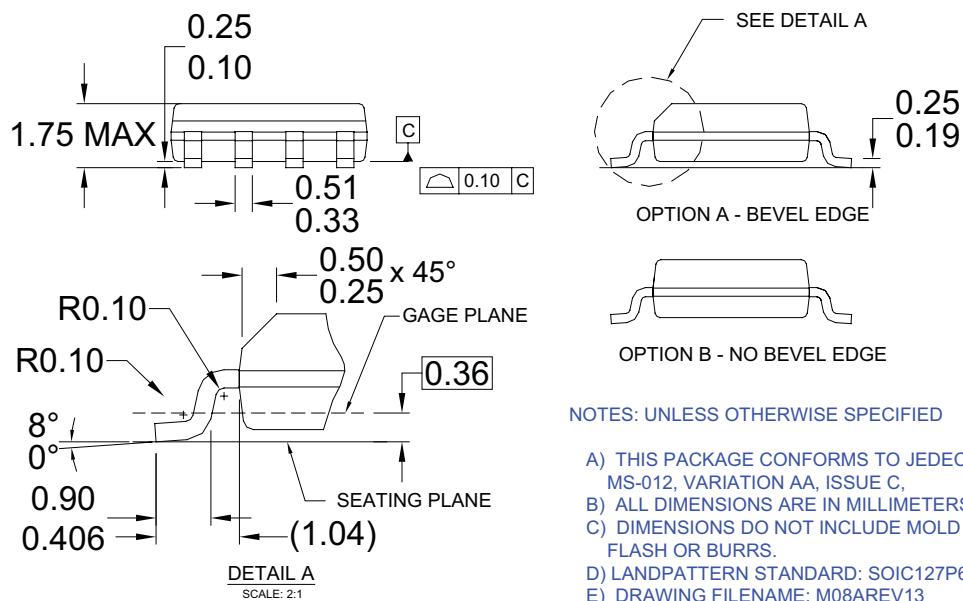
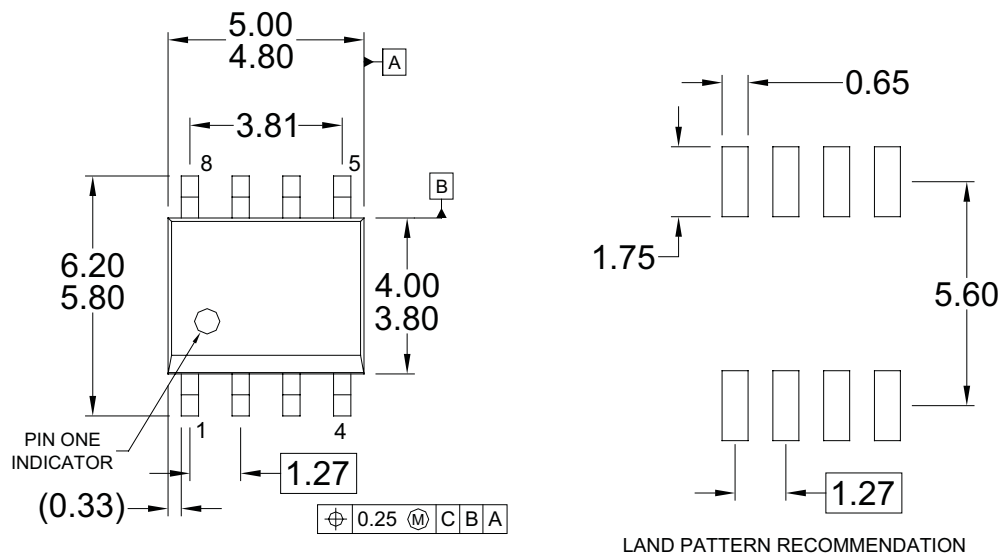


Figure 23. 8-Lead Small Outline Package (SOP)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

Auto-SPM™
 Build it Now™
 CorePLUS™
 CorePOWER™
 CROSSVOLT™
 CTL™
 Current Transfer Logic™
 EcoSPARK®
 EfficientMax™
 EZSWITCH™
 EZ™
 F®
 Fairchild®
 Fairchild Semiconductor®
 FACT Quiet Series™
 FACT®
 FAST®
 FastvCore™
 FETBench™
 FlashWriter®
 FPS™

F-PFS™
 FRFET®
 Global Power Resource™
 Green FPS™
 Green FPS™ e-Series™
 Gmax™
 GTO™
 IntelliMAX™
 ISOPLANAR™
 MegaBuck™
 MICROCOUPLER™
 MicroFET™
 MicroPak™
 MillerDrive™
 MotionMax™
 Motion-SPM™
 OPTOLOGIC®
 OPTOPLANAR®
 PDP SPM™
 Power-SPM™

PowerTrench®
 PowerXS™
 Programmable Active Droop™
 QFET®
 QS™
 Quiet Series™
 RapidConfigure™

 Saving our world, 1mW/W/kW at a time™
 SmartMax™
 SMART START™
 SPM®
 STEALTH™
 SuperFET™
 SuperSOT™3
 SuperSOT™6
 SuperSOT™8
 SupreMOS™
 SyncFET™
 Sync-Lock™


The Power Franchise®

 TinyBoost™
 TinyBuck™
 TinyLogic®
 TINYOPTO™
 TinyPower™
 TinyPWM™
 TinyWire™
 TriFault Detect™
 TRUECURRENT™
 µSerDes™

 UHC®
 Ultra FRFET™
 UniFET™
 VCX™
 VisualMax™
 XS™

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I40